

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,903,018 B2
APPLICATION NO. : 09/915658
DATED : June 7, 2005
INVENTOR(S) : Gundu M. Sabde and Whonchee Lee

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 1,

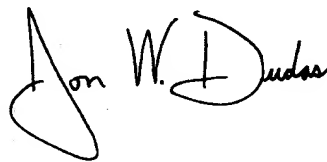
Line 11, should read -- The present invention relates to methods and apparatuses for planarizing microelectronic substrate assemblies and, more particularly, to mechanical and/or chemical-mechanical planarization of such substrate assemblies using non-abrasive planarizing solutions and fixed-abrasive polishing pads --.

Column 4,

Line 60, "160 can be glycerol, polyethylene glycol polypropylene" should read -- 160 can be glycerol, polyethylene glycol, polypropylene --.

Signed and Sealed this

Twenty-seventh Day of June, 2006

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, looped initial "J" and a cursive "Dudas".

JON W. DUDAS
Director of the United States Patent and Trademark Office